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Search Results -

Terms	Documents
110 and (embed\$4 or bury or buried or buries)	8

Database:

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IBM Technical Disclosure Bulletins	▼

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Search History

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<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
JPAB,EPAB,DWPI	110 and (embed\$4 or bury or buried or buries)	8	L12
JPAB,EPAB,DWPI	110 and (cure\$1 and curing)	45	L11
JPAB,EPAB,DWPI	filler same resin same component and (circuit or module)	360	L10
JPAB,EPAB,DWPI	filler and resin and component	12625	L9
JPAB,EPAB,DWPI	17 and filler and resin and component	12	L8
JPAB,EPAB,DWPI	nakatani	9382	L7
JPAB,EPAB,DWPI	09321178	2	L6
JPAB,EPAB,DWPI	05283608	2	L5
JPAB,EPAB,DWPI	5283608	2	L4
JPAB,EPAB,DWPI	689242	4	L3
JPAB,EPAB,DWPI	2138205	5	L2
JPAB,EPAB,DWPI	2138205	5	L1

	Hits	Search Text	DBs
1	1	6038133.pn.	USPAT
2	17	4299873.PN. OR 4417297.PN. OR 4800459.PN. OR 5045381.PN. OR 5153987.PN. OR 5324687.PN. OR 5401688.PN. OR 5401913.PN. OR 5412538.PN. OR 5481795.PN. OR 5484647.PN. OR 5651179.PN. OR 5652042.PN. OR 5677045.PN. OR 5806177.PN. OR 5888627.PN. OR 5939782.PN.	USPAT
3	0	6038133.URPN.	USPAT
4	0	6038133.URPN.	USPAT
5	5630	156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls.	USPAT
6	1287173	component or chip	USPAT
7	351679	thermoset or resin	USPAT
8	776860	circuit or wiring	USPAT
9	319	156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls. and (component or chip) and (thermoset or resin) and (circuit or wiring)	USPAT
10	228192	bury or buried or buries or embed\$3 or encapsulat\$3	USPAT
11	129	((component or chip) same (bury or buried or buries or embed\$3 or encapsulat\$3) and 156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls.	USPAT
12	89	((component or chip) same (bury or buried or buries or embed\$3 or encapsulat\$3) and 156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls.) not (156/230,233,235,247,249,289,298,299,30 03.1,307.1,307.7.ccls. and (component or chip) and (thermoset or resin) and (circuit or wiring))	USPAT
13	123	156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls. and (thermoset or resin) and (circuit or wiring) and (bury or buried or buries or embed\$3 or encapsulat\$3)	USPAT

	Hits	Search Text	DBs
14	21	(156/230,233,235,247,249,289,298,299,303.1,307.1,307.7.ccls. and (thermoset or resin) and (circuit or wiring) and (bury or buried or buries or embed\$3 or encapsulat\$3)) not (156/230,233,235,247,249,289,298,299,303.1,307.1,307.7.ccls. and (component or chip) and (thermoset or resin) and (circuit or wiring))	USPAT

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	5630	156/230,233,235,247,249,289,298,299,303.1,307.1,307.7.ccls.	USPAT	2001/02/06 13:32
2	L2	22	1 and (bury or buried or buries or embed\$3 or encapsulat\$3) same module	USPAT	2001/02/06 13:58
3	L3	1	6143116.pn.	USPAT	2001/02/06 13:44
4	L4	12	2692190.PN. OR 2969300.PN. OR 4751126.PN. OR 4869767.PN. OR 4889584.PN. OR 4912020.PN. OR 5309629.PN. OR 5744758.PN. OR 5746868.PN. OR 5817404.PN. OR 5848466.PN. OR 5925930.PN.	USPAT	2001/02/06 13:44
5	L5	1766	(bury or buried or buries or embed\$4 or encapsulat\$3) same (component or chip) same module	USPAT	2001/02/06 14:00
6	L6	92	5 and (thermoset\$4 or resin) and filler	USPAT	2001/02/06 14:13
7	L7	450	5 and (thermoset\$4 or resin)	USPAT	2001/02/06 14:14
8	L8	448	7 and (circuit or wiring or via or through ad hole)	USPAT	2001/02/06 14:15
9.	L9	356	8 not 6	USPAT	2001/02/06 14:16